

Customer No.: 31561  
Application No.: 10/707,825  
Docket NO.: 10786-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

1. (original) A flip-chip gold bump structure formed on a wafer, comprising:  
at least one gold bump;  
a nickel layer on the gold bump; and  
a copper layer on the nickel layer.

2. (original) The flip-chip gold bump structure of claim 1, wherein the nickel layer  
has a thickness about from 0.1  $\mu$ m to about 20  $\mu$ m.

3. (original) The flip-chip gold bump structure of claim 1, wherein the copper  
layer has a thickness about from 0.1  $\mu$ m to about 10  $\mu$ m.

4. (original) The flip-chip gold bump structure of claim 1, wherein the gold bump  
has a height about from 3  $\mu$ m to about 150  $\mu$ m.

5. (original) A flip-chip package structure adapted to connect a chip and a chip  
substrate, comprising:

at least one gold bump on the chip;

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a nickel layer on the gold bump; and  
a solder containing copper on the nickel layer for connecting the chip and the chip substrate.

6. (original) The flip-chip package structure of claim 5, wherein the solder containing copper includes a solder alloy.

7. (original) The flip-chip package structure of claim 6, wherein copper in the solder alloy is from about 0.7 wt.% to about 3.0 wt.%.

8. (original) The flip-chip package structure of claim 5, wherein the nickel layer has a thickness about from 0.1  $\mu$ m to about 20  $\mu$ m.

9. (original) The flip-chip package structure of claim 5, wherein the gold bump has a height about from 3  $\mu$ m to about 150  $\mu$ m.

Claims 10-22 (canceled).